

描述 / Descriptions

超快恢复二极管，反向电压：800V，正向电流：2.0A，SMB 封装。

Surface Mount Superfast Recovery Rectifier,Reverse Voltage:800V,Forward Current:2.0A, SMB package.

特征 / Features

玻璃钝化芯片，反向恢复时间快，无铅符合 2011/65/EU 欧盟 RoHS 指令，适用于表面贴装。无卤产品。

Glass Passivated Chip Superfast reverse recovery time, Lead free in comply with EU R0HS 2011/65/EU directives,For surface mounted applications,Halogen free product.

用途 / Applications

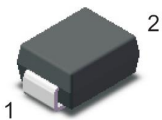
一般用途.

General purpose.

内部等效电路 / Equivalent Circuit

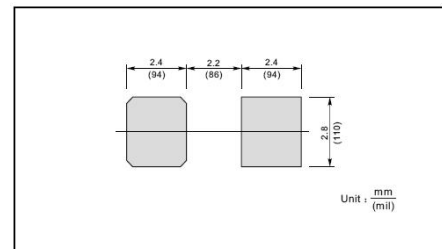


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。 See Marking Instructions

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
		ES2AB	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	800	V
Maximum RMS voltage	V_{RMS}	560	V
Maximum DC Blocking Voltage	V_{DC}	800	V
Maximum Average Forward Rectified Current at $T_c=125^\circ\text{C}$	$I_{F(AV)}$	2.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	60	A
Typical Junction Capacitance at $V_R=4\text{V}$, $f=1\text{MHz}$	C_j	40	pF
Typical Thermal Resistance ⁽¹⁾	$R_{\theta JA}$	60	°C/W
	$R_{\theta JC}$	20	
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150	°C

Note:

(1) P.C.B. mounted with 2.0 X 2.0" (5 X 5 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
			ES2KB	
Maximum Forward Voltage	V_F	$I_F=2.0\text{A}$	1.70	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ\text{C}$	5.0	μA
		$T_a=125^\circ\text{C}$	100	μA
Maximum Reverse Recovery Time	t_{rr}	$I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	35	ns

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram

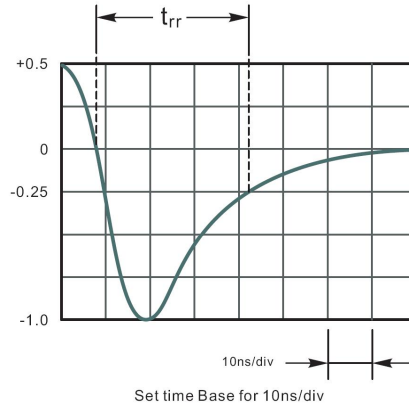
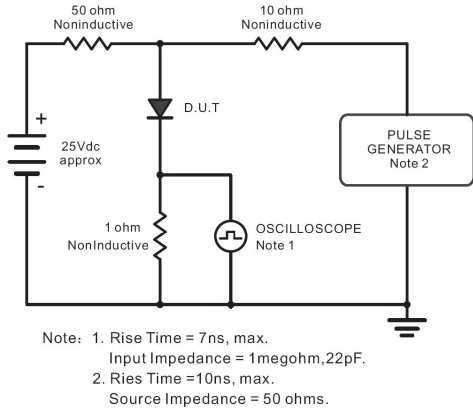


Fig.2 Maximum Average Forward Current Rating

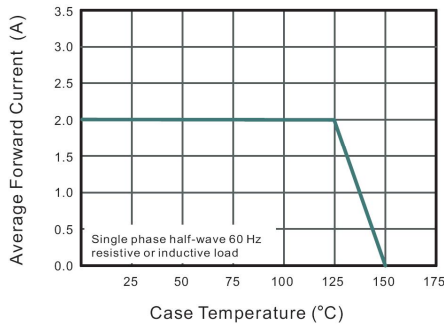


Fig.3 Typical Reverse Characteristics

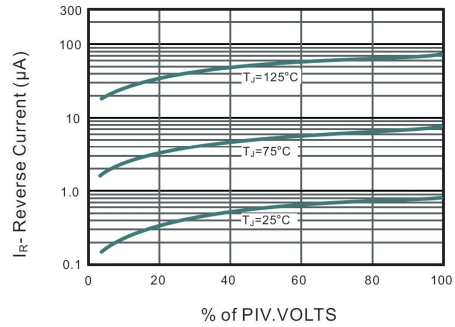


Fig.4 Typical Forward Characteristics

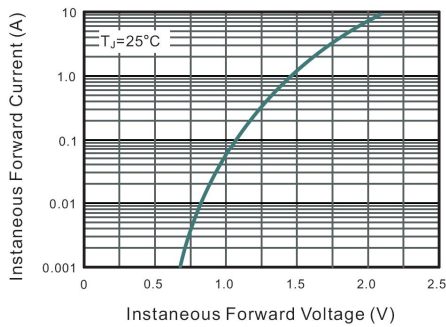


Fig.5 Typical Junction Capacitance

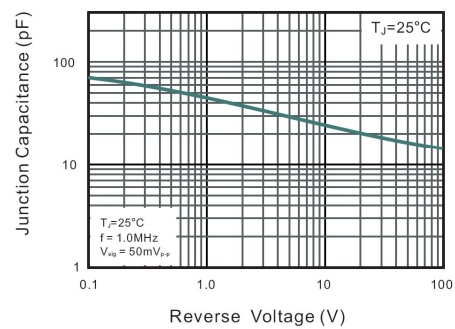
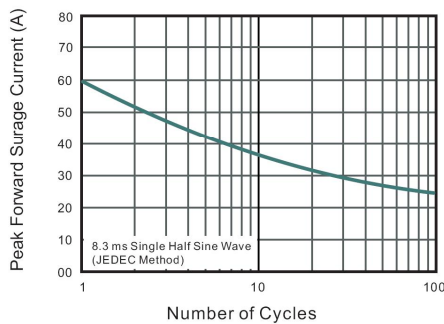
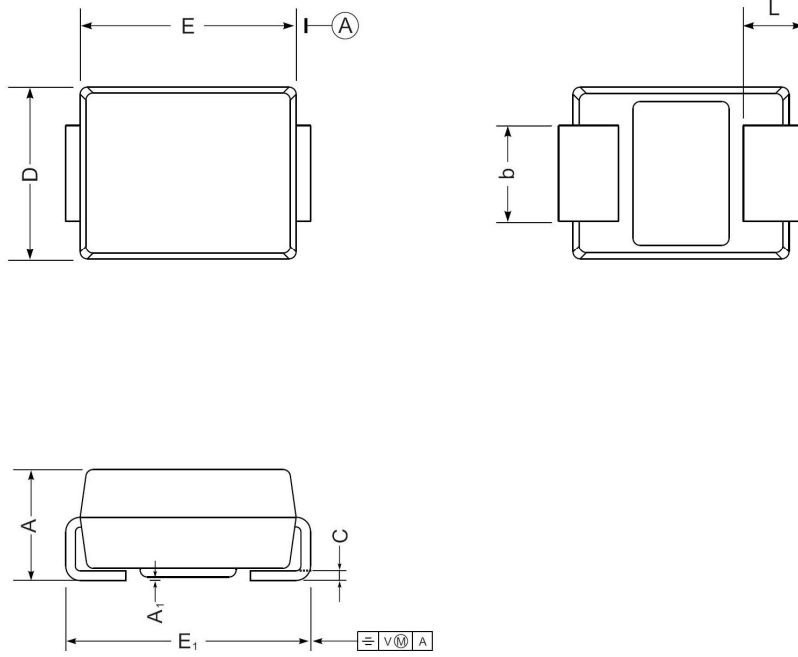


Fig.6 Maximum Non-Repetitive Forward Surge Current



外形尺寸图 / Package Dimensions

SMB



SMB mechanical data

UNIT		A	E	D	E_1	A_1	L	C	b
mm	max	2.44	4.70	3.94	5.59	0.20	1.5	0.305	2.2
	min	2.13	4.06	3.3	5.08	0.05	0.8	0.152	1.9
mil	max	96	185	155	220	7.9	59	12	87
	min	84	160	130	200	2.0	32	6	75

印章说明 / Marking Instructions



说明：

ES2K： 为型号代码

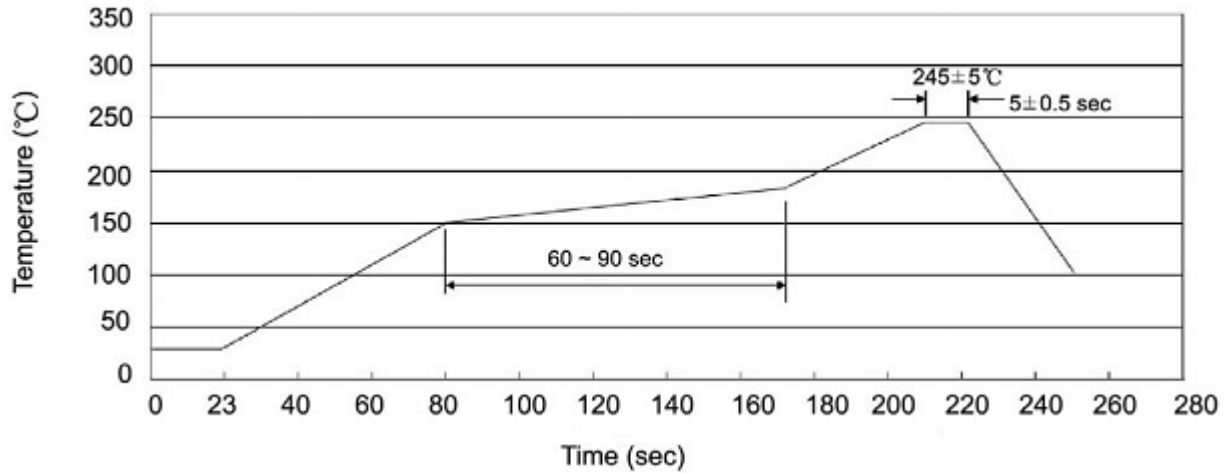
****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

ES2K： Product Type Code

****： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No
Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 $25 \sim 150^\circ\text{C}$ ，时间 $60 \sim 90\text{sec}$;
- 2、峰值温度 $245 \pm 5^\circ\text{C}$ ，时间持续为 $5 \pm 0.5\text{sec}$;
- 3、焊接制程冷却速度为 $2 \sim 10^\circ\text{C}/\text{sec}$.

Note:

- 1.Preheating: $25 \sim 150^\circ\text{C}$, Time: $60 \sim 90\text{sec}$.
- 2.Peak Temp.: $245 \pm 5^\circ\text{C}$, Duration: $5 \pm 0.5\text{sec}$.
3. Cooling Speed: $2 \sim 10^\circ\text{C}/\text{sec}$.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度： $260 \pm 5^\circ\text{C}$ 时间： 10 ± 1 sec. Temp.: $260 \pm 5^\circ\text{C}$ Time: 10 ± 1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMB	3000	5	15000	5	75000	7" × 11	185X180X105	390X385X205

使用说明 / Notices